



Material Content Data Sheet



Sales Product Name				AIHD04N60R		Issued		25. January 2018	
MA#				MA001372414					
Package				PG-TO252-3-313		Weight*		316.69 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.692	0.22	0.22	2186	2186	
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		140		
	non noble metal	iron	7439-89-6	0.147	0.05		465		
	non noble metal	copper	7440-50-8	147.096	46.43	46.49	464486	465091	
	non noble metal	aluminium	7429-90-5	0.530	0.17	0.17	1673	1673	
wire	non noble metal	aluminium	7429-90-5	0.530	0.17	0.17	1673	1673	
encapsulation	organic material	carbon black	1333-86-4	1.430	0.45		4514		
	plastics	epoxy resin	-	25.017	7.90		78998		
	inorganic material	silicondioxide	60676-86-0	116.510	36.79	45.14	367904	451416	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11810	11810	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4486	4497	
solder	non noble metal	tin	7440-31-5	0.017	0.01		54		
	noble metal	silver	7440-22-4	0.021	0.01		67		
	non noble metal	lead	7439-92-1	0.814	0.26	0.28	2570	2691	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	iron	7439-89-6	0.019	0.01		61		
	non noble metal	copper	7440-50-8	19.177	6.06	6.07	60557	60636	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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